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Details

Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPS
Connectivity	I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I ² S, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	48K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 18x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512gm304-i-ml

dsPIC33EPXXXGM3XX/6XX/7XX

TABLE 2: PIN NAMES: dsPIC33EP128/256/512GM310/710 DEVICES^(1,2,3) (CONTINUED)

Pin #	Full Pin Name	Pin #	Full Pin Name
E1	PWM6H/T8CK/RD4	J8	No Connect
E2	PWM6L/T9CK/RD3	J9	No Connect
E3	AN19/RP118/PMA5/RG6	J10	AN41/RP81/RE1
E4	PWM5H/RD2	J11	AN30/SDA1/RPI52/RC4
E5	No Connect	K1	PGED3/OA2IN-/AN2/C2IN1-/SS1/RPI32/CTED2/RB0
E6	RP113/RG1	K2	PGEC3/CVREF+/OA1OUT/AN3/C1IN4-/C4IN2-/RPI33/CTED1/RB1
E7	No Connect	K3	VREF+/AN34/PMA7/RF10
K4	OA3OUT/AN6/C3IN4-/C4IN4-/C4IN1+/RP48/OCFB/RC0	L3	AVss
K5	No Connect	L4	OA3IN-/AN7/C3IN1-/C4IN1-/RP49/RC1
K6	AN37/RF12	L5	OA3IN+/AN8/C3IN3-/C3IN1+/RPI50/U1RTS/BCLK1/FLT3/PMA13/RC2
K7	AN14/RPI94/FLT7/PMA1/RE14	L6	AN36/RF13
K8	VDD	L7	AN13/C3IN2-/U2CTS/FLT6/PMA10/RE13
K9	AN39/RD15	L8	AN15/RPI95/FLT8/PMA0/RE15
K10	OA5IN+/AN24/C5IN3-/C5IN1+/SDO1/RP20/T1CK/RA4	L9	AN38/RD14
K11	AN40/RPI80/RE0	L10	SDA2/RPI24/PMA9/RA8
L1	PGEC1/OA1IN+/AN4/C1IN3-/C1IN1+/C2IN3-/RPI34/RB2	L11	FLT32/SCL2/RP36/PMA8/RB4
L2	VREF-/AN33/PMA6/RF9		

Note 1: The RPN/RPIN pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.

2: Every I/O port pin (RAX-RGx) can be used as a Change Notification pin (CNAX-CNGx). See **Section 11.0 “I/O Ports”** for more information.

3: The availability of I²C™ interfaces varies by device. Selection (SDAx/SCLx or ASDAx/ASCLx) is made using the device Configuration bits, ALTI2C1 and ALTI2C2 (FPOR<5.4>). See **Section 30.0 “Special Features”** for more information.

TABLE 4-4: TIMERS REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TMR1	0100	Timer1 Register																0000
PR1	0102	Period Register 1																FFFF
T1CON	0104	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	TSYNC	TCS	—	0000
TMR2	0106	Timer2 Register																0000
TMR3HLD	0108	Timer3 Holding Register (For 32-bit timer operations only)																xxxx
TMR3	010A	Timer3 Register																0000
PR2	010C	Period Register 2																FFFF
PR3	010E	Period Register 3																FFFF
T2CON	0110	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000
T3CON	0112	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000
TMR4	0114	Timer4 Register																0000
TMR5HLD	0116	Timer5 Holding Register (For 32-bit timer operations only)																xxxx
TMR5	0118	Timer5 Register																0000
PR4	011A	Period Register 4																FFFF
PR5	011C	Period Register 5																FFFF
T4CON	011E	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000
T5CON	0120	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000
TMR6	0122	Timer6 Register																0000
TMR7HLD	0124	Timer7 Holding Register (For 32-bit timer operations only)																xxxx
TMR7	0126	Timer7 Register																0000
PR6	0128	Period Register 6																FFFF
PR7	012A	Period Register 7																FFFF
T6CON	012C	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000
T7CON	012E	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000
TMR8	0130	Timer8 Register																0000
TMR9HLD	0132	Timer9 Holding Register (For 32-bit timer operations only)																xxxx
TMR9	0134	Timer9 Register																0000
PR8	0136	Period Register 8																FFFF
PR9	0138	Period Register 9																FFFF
T8CON	013A	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000
T9CON	013C	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

5.2 RTSP Operation

RTSP allows the user application to erase a single page of memory, program a row and to program two instruction words at a time. See Table 1 in the “dsPIC33EPXXXGM3XX/6XX/7XX Product Family” section for the page sizes of each device.

The Flash program memory array is organized into rows of 64 instructions or 192 bytes. RTSP allows the user application to erase a page of program memory, which consists of eight rows (512 instructions) at a time, and to program one row or two adjacent words at a time. The 8-row erase pages and single row write rows are edge-aligned, from the beginning of program memory, on boundaries of 1536 bytes and 192 bytes, respectively.

For more information on erasing and programming Flash memory, refer to the “dsPIC33/PIC24 Family Reference Manual”, “Flash Programming” (DS70609).

5.3 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. The processor stalls (waits) until the programming operation is finished.

For erase and program times, refer to Parameters D137a and D137b (Page Erase Time), and D138a and D138b (Word Write Cycle Time), in Table 33-13.

Setting the WR bit (NVMCON<15>) starts the operation and the WR bit is automatically cleared when the operation is finished.

5.3.1 PROGRAMMING ALGORITHM FOR FLASH PROGRAM MEMORY

Programmers can program two adjacent words (24 bits x 2) of program Flash memory at a time on every other word address boundary (0x000002, 0x000006, 0x00000A, etc.). To do this, it is necessary to erase the page that contains the desired address of the location the user wants to change. Programmers can also program a row of data (64 instruction words/192 bytes) at a time using the row programming feature present in these devices. For row programming, the source data is fetched directly from the data memory (RAM) on these devices. Two new registers have been provided to point to the RAM location where the source data resides. The page that has the row to be programmed must first be erased before the programming operation.

For protection against accidental operations, the write initiate sequence for NVMKEY must be used to allow any erase or program operation to proceed. After the programming command has been executed, the user application must wait for the programming time until programming is complete. The two instructions following the start of the programming sequence should be NOPS.

Refer to the “dsPIC33/PIC24 Family Reference Manual”, “Flash Programming” (DS70609) for details and code examples on programming using RTSP.

5.4 Control Registers

Six SFRs are used to read and write the program Flash memory: NVMCON, NVMKEY, NVMADR, NVMADRU, NVMSRCADRL and NVMSRCADRH.

The NVMCON register (Register 5-1) controls which blocks are to be erased, which memory type is to be programmed and the start of the programming cycle.

NVMKEY (Register 5-4) is a write-only register that is used for write protection. To start a programming or erase sequence, the user application must consecutively write 0x55 and 0xAA to the NVMKEY register.

There are two NVM Address registers: NVMADRU and NVMADR. These two registers, when concatenated, form the 24-bit Effective Address (EA) of the selected word for programming operations, or the selected page for erase operations.

The NVMADRU register is used to hold the upper 8 bits of the EA, while the NVMADR register is used to hold the lower 16 bits of the EA.

The NVMSRCADRH and NVMSRCADRL registers are used to hold the source address of the data in the data memory that needs to be written to Flash memory.

dsPIC33EPXXXGM3XX/6XX/7XX

REGISTER 6-1: RCON: RESET CONTROL REGISTER⁽¹⁾

R/W-0	R/W-0	U-0	U-0	R/W-0	U-0	R/W-0	R/W-0
TRAPR	IOPUWR	—	—	VREGSF	—	CM	VREGS
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1
EXTR	SWR	SWDTEN ⁽²⁾	WDTO	SLEEP	IDLE	BOR	POR
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 15 **TRAPR:** Trap Reset Flag bit
1 = A Trap Conflict Reset has occurred
0 = A Trap Conflict Reset has not occurred
- bit 14 **IOPUWR:** Illegal Opcode or Uninitialized W Access Reset Flag bit
1 = An illegal opcode detection, an illegal address mode or Uninitialized W register used as an Address Pointer caused a Reset
0 = An illegal opcode or Uninitialized W Register Reset has not occurred
- bit 13-12 **Unimplemented:** Read as '0'
- bit 11 **VREGSF:** Flash Voltage Regulator Standby During Sleep bit
1 = Flash Voltage regulator is active during Sleep
0 = Flash Voltage regulator goes into Standby mode during Sleep
- bit 10 **Unimplemented:** Read as '0'
- bit 9 **CM:** Configuration Mismatch Flag bit
1 = A Configuration Mismatch Reset has occurred.
0 = A Configuration Mismatch Reset has NOT occurred
- bit 8 **VREGS:** Voltage Regulator Standby During Sleep bit
1 = Voltage regulator is active during Sleep
0 = Voltage regulator goes into Standby mode during Sleep
- bit 7 **EXTR:** External Reset ($\overline{\text{MCLR}}$) Pin bit
1 = A Master Clear (pin) Reset has occurred
0 = A Master Clear (pin) Reset has not occurred
- bit 6 **SWR:** Software RESET (Instruction) Flag bit
1 = A RESET instruction has been executed
0 = A RESET instruction has not been executed
- bit 5 **SWDTEN:** Software Enable/Disable of WDT bit⁽²⁾
1 = WDT is enabled
0 = WDT is disabled
- bit 4 **WDTO:** Watchdog Timer Time-out Flag bit
1 = WDT time-out has occurred
0 = WDT time-out has not occurred

Note 1: All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

NOTES:

dsPIC33EPXXXGM3XX/6XX/7XX

9.1 CPU Clocking System

The dsPIC33EPXXXGM3XX/6XX/7XX family of devices provides seven system clock options:

- Fast RC (FRC) Oscillator
- FRC Oscillator with Phase-Locked Loop (PLL)
- FRC Oscillator with Postscaler
- Primary (XT, HS or EC) Oscillator
- Primary Oscillator with PLL
- Low-Power RC (LPRC) Oscillator
- Secondary (LP) Oscillator

Instruction execution speed or device operating frequency, F_{CY} , is given by Equation 9-1.

EQUATION 9-1: DEVICE OPERATING FREQUENCY

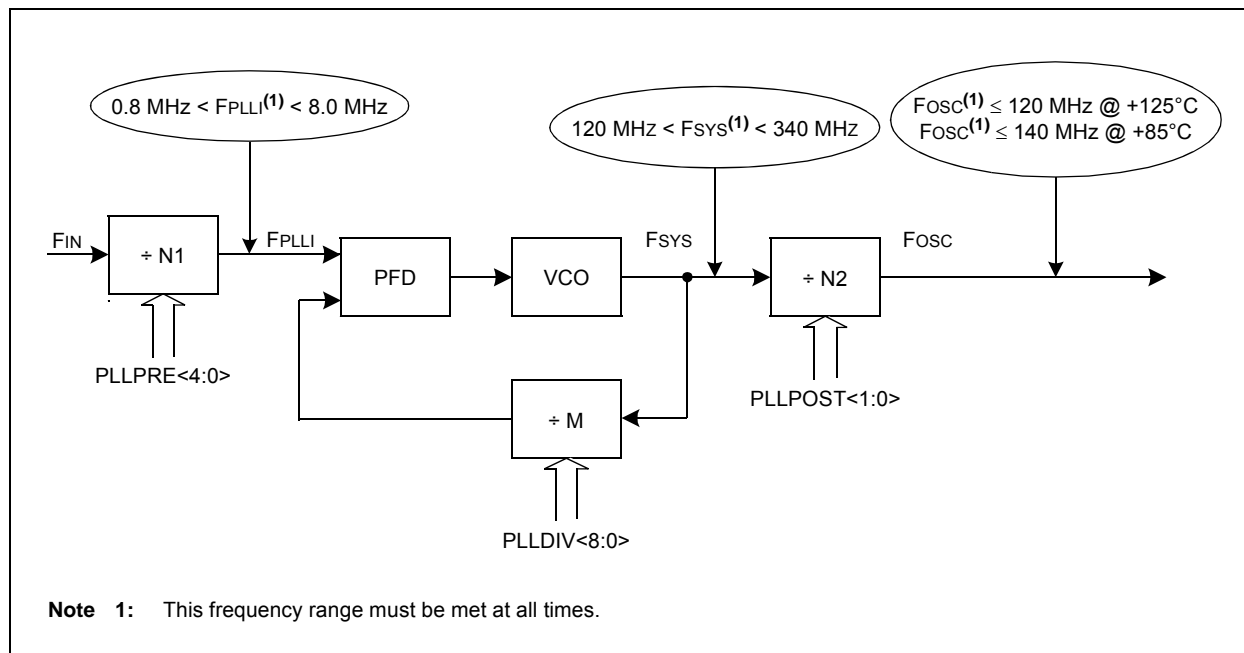
$$F_{CY} = F_{OSC}/2$$

Figure 9-2 is a block diagram of the PLL module.

Equation 9-2 provides the relationship between input frequency (F_{IN}) and output frequency (F_{OSC}).

Equation 9-3 provides the relationship between input frequency (F_{IN}) and VCO frequency (F_{SYS}).

FIGURE 9-2: PLL BLOCK DIAGRAM



EQUATION 9-2: F_{OSC} CALCULATION

$$F_{OSC} = F_{IN} \times \left(\frac{M}{N1 \times N2} \right) = F_{IN} \times \left(\frac{(PLLDIV<8:0> + 2)}{((PLLPRE<4:0> + 2) \times 2(PLLPOST<1:0> + 1))} \right)$$

Where:

$$N1 = PLLPRE<4:0> + 2$$

$$N2 = 2 \times (PLLPOST<1:0> + 1)$$

$$M = PLLDIV<8:0> + 2$$

EQUATION 9-3: F_{VCO} CALCULATION

$$F_{SYS} = F_{IN} \times \left(\frac{M}{N1} \right) = F_{IN} \times \left(\frac{(PLLDIV<8:0> + 2)}{(PLLPRE<4:0> + 2)} \right)$$

REGISTER 9-4: OSCTUN: FRC OSCILLATOR TUNING REGISTER⁽¹⁾

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	TUN<5:0>					
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-6 **Unimplemented:** Read as '0'

bit 5-0 **TUN<5:0>:** FRC Oscillator Tuning bits

111111 = Center frequency – 0.047%

•

•

•

100001 = Center frequency – 1.453%

100000 = Center frequency – 1.5% (7.355 MHz)

011111 = Center frequency + 1.5% (7.385 MHz)

011110 = Center frequency + 1.453%

•

•

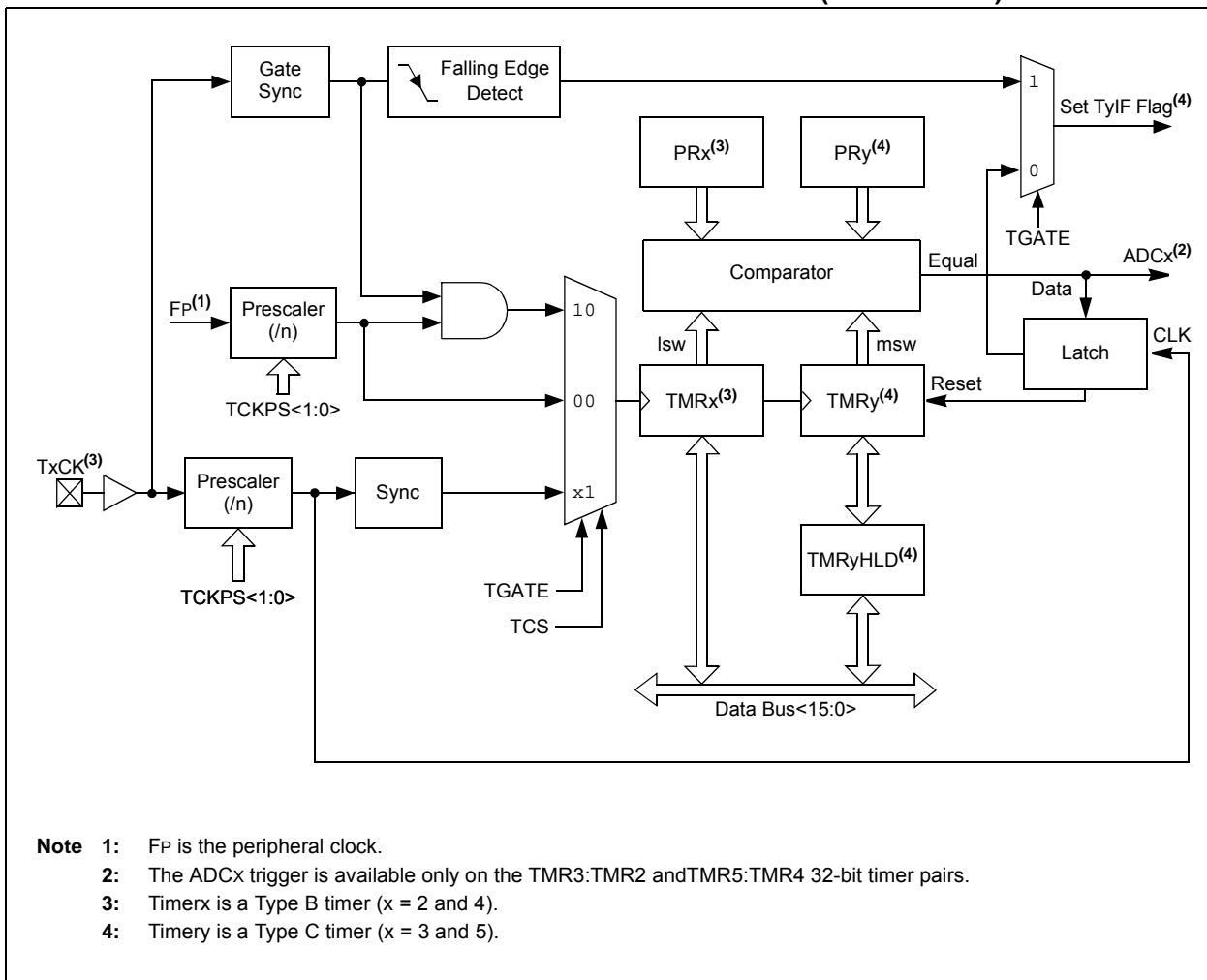
•

000001 = Center frequency + 0.047%

000000 = Center frequency (7.3728 MHz nominal)

Note 1: This register resets only on a Power-on Reset (POR).

FIGURE 13-3: TYPE B/TIME C TIMER PAIR BLOCK DIAGRAM (32-BIT TIMER)



REGISTER 16-1: PTCON: PWMx TIME BASE CONTROL REGISTER (CONTINUED)

bit 6-4 **SYNCSRC<2:0>**: Synchronous Source Selection bits⁽¹⁾

111 = Reserved

•

•

100 = Reserved

011 = PTGO17⁽²⁾

010 = PTGO16⁽²⁾

001 = Reserved

000 = SYNCI1

bit 3-0 **SEVTPS<3:0>**: PWMx Special Event Trigger Output Postscaler Select bits⁽¹⁾

1111 = 1:16 Postscaler generates Special Event Trigger on every sixteenth compare match event

•

•

•

0001 = 1:2 Postscaler generates Special Event Trigger on every second compare match event

0000 = 1:1 Postscaler generates Special Event Trigger on every compare match event

Note 1: These bits should be changed only when PTEN = 0. In addition, when using the SYNCI1 feature, the user application must program the Period register with a value that is slightly larger than the expected period of the external synchronization input signal.

2: See Section 25.0 “Peripheral Trigger Generator (PTG) Module” for information on this selection.

REGISTER 16-23: LEBDLYx: LEADING-EDGE BLANKING DELAY REGISTER x

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	LEB<11:8>			
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
LEB<7:0>							
bit 7				bit 0			

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'

bit 11-0 **LEB<11:0>:** Leading-Edge Blanking Delay for Current-Limit and Fault Inputs bits

REGISTER 21-16: CxRXFnSID: CANx ACCEPTANCE FILTER n STANDARD IDENTIFIER REGISTER (n = 0-15)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID10	SID9	SID8	SID7	SID6	SID5	SID4	SID3
bit 15							bit 8

R/W-x	R/W-x	R/W-x	U-0	R/W-x	U-0	R/W-x	R/W-x
SID2	SID1	SID0	—	EXIDE	—	EID17	EID16
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 15-5 **SID<10:0>**: Standard Identifier bits
 1 = Message address bit, SIDx, must be '1' to match filter
 0 = Message address bit, SIDx, must be '0' to match filter
- bit 4 **Unimplemented**: Read as '0'
- bit 3 **EXIDE**: Extended Identifier Enable bit
If MIDE = 1:
 1 = Matches only messages with Extended Identifier addresses
 0 = Matches only messages with Standard Identifier addresses
If MIDE = 0:
 Ignores EXIDE bit.
- bit 2 **Unimplemented**: Read as '0'
- bit 1-0 **EID<17:16>**: Extended Identifier bits
 1 = Message address bit, EIDx, must be '1' to match filter
 0 = Message address bit, EIDx, must be '0' to match filter

REGISTER 21-17: CxRXFnEID: CANx ACCEPTANCE FILTER n EXTENDED IDENTIFIER REGISTER (n = 0-15)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID<15:8>							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID<7:0>							
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 15-0 **EID<15:0>**: Extended Identifier bits
 1 = Message address bit, EIDx, must be '1' to match filter
 0 = Message address bit, EIDx, must be '0' to match filter

TABLE 25-1: PTG STEP COMMAND FORMAT (CONTINUED)

bit 3-0	Step Command	OPTION<3:0>	Option Description
	PTGCTRL ⁽¹⁾	0000	Reserved
		0001	Reserved
		0010	Disable Step Delay Timer (PTGSD)
		0011	Reserved
		0100	Reserved
		0101	Reserved
		0110	Enable Step Delay Timer (PTGSD)
		0111	Reserved
		1000	Start and wait for the PTG Timer0 to match Timer0 Limit register
		1001	Start and wait for the PTG Timer1 to match Timer1 Limit register
		1010	Reserved
		1011	Wait for software trigger bit transition from low-to-high before continuing (PTGSWT = 0 to 1)
		1100	Copy contents of the Counter 0 register to the AD1CHS0 register
		1101	Copy contents of the Counter 1 register to the AD1CHS0 register
		1110	Copy contents of the Literal 0 register to the AD1CHS0 register
		1111	Generate the triggers indicated in the PTG Broadcast Trigger Enable register (PTGBTE)
	PTGADD ⁽¹⁾	0000	Add contents of PTGADJ register to the Counter 0 Limit register (PTGC0LIM)
		0001	Add contents of PTGADJ register to the Counter 1 Limit register (PTGC1LIM)
		0010	Add contents of PTGADJ register to the Timer0 Limit register (PTGT0LIM)
		0011	Add contents of PTGADJ register to the Timer1 Limit register (PTGT1LIM)
		0100	Add contents of PTGADJ register to the Step Delay Limit register (PTGSDLIM)
		0101	Add contents of PTGADJ register to the Literal 0 register (PTGL0)
		0110	Reserved
		0111	Reserved
	PTGCOPY ⁽¹⁾	1000	Copy contents of PTGHOLD register to the Counter 0 Limit register (PTGC0LIM)
		1001	Copy contents of PTGHOLD register to the Counter 1 Limit register (PTGC1LIM)
		1010	Copy contents of PTGHOLD register to the Timer0 Limit register (PTGT0LIM)
		1011	Copy contents of PTGHOLD register to the Timer1 Limit register (PTGT1LIM)
		1100	Copy contents of PTGHOLD register to the Step Delay Limit register (PTGSDLIM)
		1101	Copy contents of PTGHOLD register to the Literal 0 register (PTGL0)
		1110	Reserved
		1111	Reserved

Note 1: All reserved commands or options will execute but have no effect (i.e., execute as a NOP instruction).

2: Refer to Table 25-2 for the trigger output descriptions.

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REGISTER 28-5: PMSTAT: PARALLEL MASTER PORT STATUS REGISTER (SLAVE MODE ONLY)⁽¹⁾

R-0	R/W-0, HS	U-0	U-0	R-0	R-0	R-0	R-0
IBF	IBOV	—	—	IB3F	IB2F	IB1F	IB0F
bit 15							bit 8

R-1	R/W-0, HS	U-0	U-0	R-1	R-1	R-1	R-1
OBE	OBUE	—	—	OB3E	OB2E	OB1E	OB0E
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at Reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

- bit 15 **IBF:** Input Buffer Full Status bit
1 = All writable Input Buffer registers are full
0 = Some or all of the writable Input Buffer registers are empty
- bit 14 **IBOV:** Input Buffer Overflow Status bit
1 = A write attempt to a full Input Byte register occurred (must be cleared in software)
0 = No overflow occurred
- bit 13-12 **Unimplemented:** Read as '0'
- bit 11-8 **IB3F:IB0F:** Input Buffer x Status Full bit
1 = Input Buffer x contains data that has not been read (reading buffer will clear this bit)
0 = Input Buffer x does not contain any unread data
- bit 7 **OBE:** Output Buffer Empty Status bit
1 = All readable Output Buffer registers are empty
0 = Some or all of the readable Output Buffer registers are full
- bit 6 **OBUE:** Output Buffer Underflow Status bit
1 = A read occurred from an empty Output Byte register (must be cleared in software)
0 = No underflow occurred
- bit 5-4 **Unimplemented:** Read as '0'
- bit 3-0 **OB3E:OB0E:** Output Buffer x Status Empty bit
1 = Output Buffer x is empty (writing data to the buffer will clear this bit)
0 = Output Buffer x contains data that has not been transmitted

Note 1: This register is not available on 44-pin devices.

TABLE 33-17: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ. ⁽¹⁾	Max.	Units	Conditions
OS50	FPLLI	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range	0.8	—	8.0	MHz	ECPLL, XTPLL modes
OS51	FSYS	On-Chip VCO System Frequency	120	—	340	MHz	
OS52	TLOCK	PLL Start-up Time (Lock Time)	0.9	1.5	3.1	ms	
OS53	DCLK	CLKO Stability (Jitter) ⁽²⁾	-3	0.5	3	%	

- Note 1:** Data in “Typical” column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.
- 2:** This jitter specification is based on clock cycle-by-clock cycle measurements. To get the effective jitter for individual time bases or communication clocks used by the application, use the following formula:

$$\text{Effective Jitter} = \frac{DCLK}{\sqrt{\frac{FOSC}{\text{Time Base or Communication Clock}}}}$$

For example, if FOSC = 120 MHz and the SPI bit rate = 10 MHz, the effective jitter is as follows:

$$\text{Effective Jitter} = \frac{DCLK}{\sqrt{\frac{120}{10}}} = \frac{DCLK}{\sqrt{12}} = \frac{DCLK}{3.464}$$

TABLE 33-18: INTERNAL FRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	Characteristic	Min.	Typ.	Max.	Units	Conditions	
Internal FRC Accuracy @ FRC Frequency = 7.3728 MHz ⁽¹⁾							
F20a	FRC	-1.5	0.5	+1.5	%	-40°C ≤ TA ≤ +85°C	VDD = 3.0-3.6V
F20b	FRC	-2	1.5	+2	%	-40°C ≤ TA ≤ +125°C	VDD = 3.0-3.6V

- Note 1:** Frequency calibrated at +25°C and 3.3V. TUNx bits can be used to compensate for temperature drift.

TABLE 33-19: INTERNAL LPRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	Characteristic	Min.	Typ.	Max.	Units	Conditions	
LPRC @ 32.768 kHz							
F21a	LPRC	-15	5	+15	%	-40°C ≤ TA ≤ +85°C	VDD = 3.0-3.6V
F21b	LPRC	-30	10	+30	%	-40°C ≤ TA ≤ +125°C	VDD = 3.0-3.6V

TABLE 33-32: SPI2 AND SPI3 MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Maximum Data Rate	Master Transmit Only (Half-Duplex)	Master Transmit/Receive (Full-Duplex)	Slave Transmit/Receive (Full-Duplex)	CKE	CKP	SMP
15 MHz	Table 33-33	—	—	0,1	0,1	0,1
9 MHz	—	Table 33-34	—	1	0,1	1
9 MHz	—	Table 33-35	—	0	0,1	1
15 MHz	—	—	Table 33-36	1	0	0
11 MHz	—	—	Table 33-37	1	1	0
15 MHz	—	—	Table 33-38	0	1	0
11 MHz	—	—	Table 33-39	0	0	0

FIGURE 33-15: SPI2 AND SPI3 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS

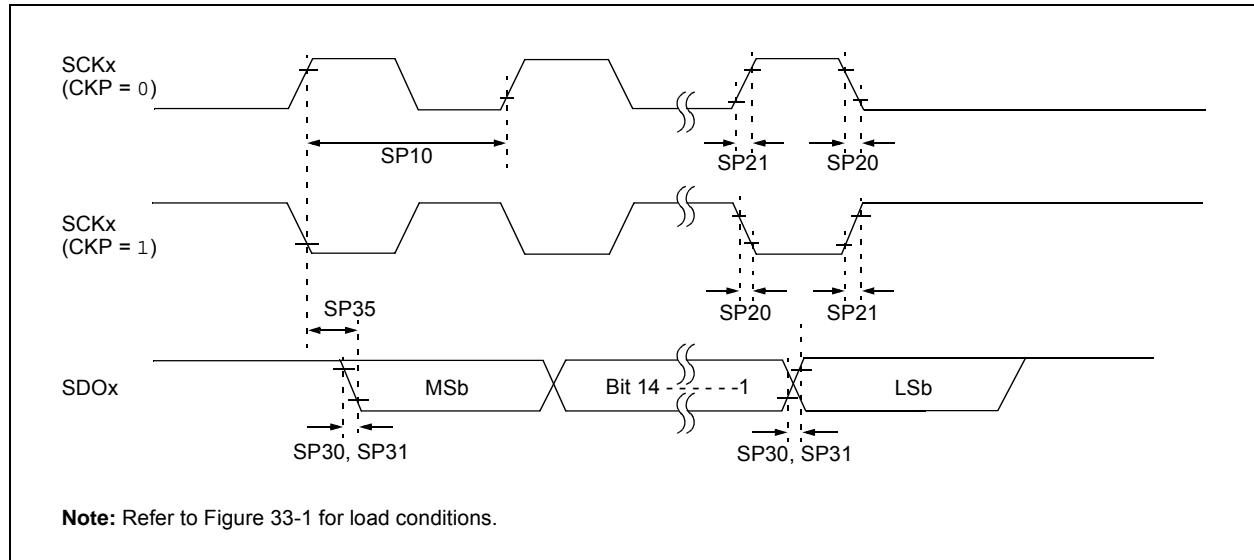


FIGURE 33-20: SPI2 AND SPI3 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

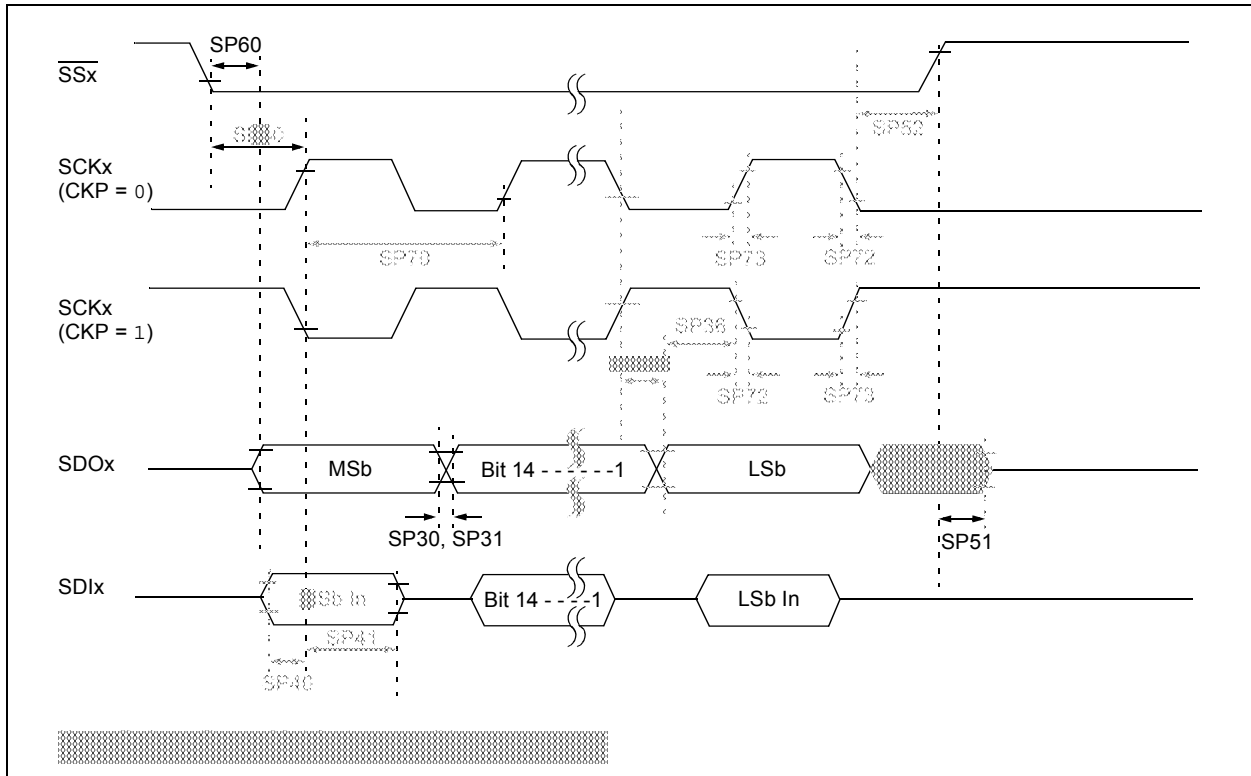
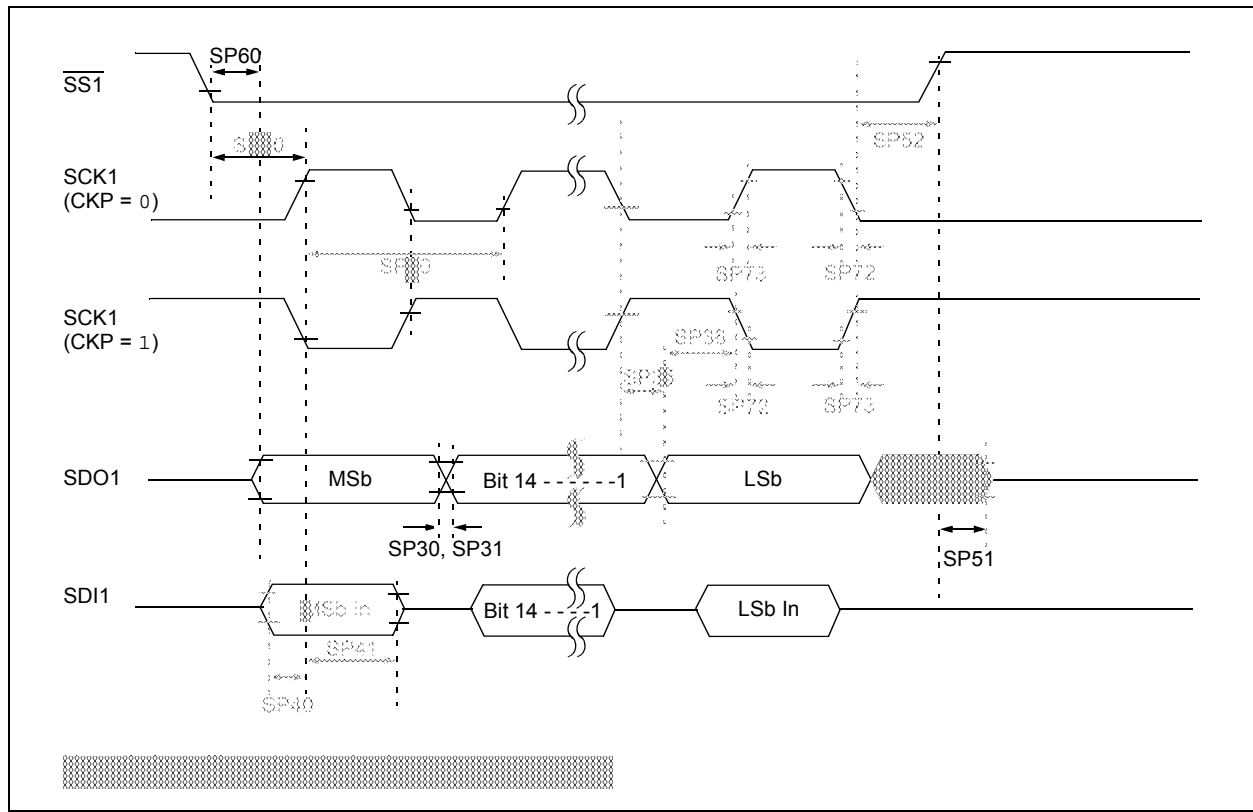


FIGURE 33-27: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0)
TIMING CHARACTERISTICS



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TABLE 33-52: OP AMP/COMPARATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 3): 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic	Min.	Typ. ⁽¹⁾	Max.	Units	Conditions
Comparator AC Characteristics							
CM10	TRESP	Response Time	—	19	—	ns	V+ input step of 100 mV, V- input held at VDD/2
CM11	TMC2OV	Comparator Mode Change to Output Valid	—	—	10	μs	
Comparator DC Characteristics							
CM30	VOFFSET	Comparator Offset Voltage	—	±20	±75	mV	
CM31	VHYST	Input Hysteresis Voltage	—	30	—	mV	
CM32	TRISE/ TFALL	Comparator Output Rise/Fall Time	—	20	—	ns	1 pF load capacitance on input
CM33	VGAIN	Open-Loop Voltage Gain	—	90	—	db	
CM34	VICM	Input Common-Mode Voltage	AVSS	—	AVDD	V	
Op Amp AC Characteristics							
CM20	SR	Slew Rate	—	9	—	V/μs	10 pF load
CM21a	PM	Phase Margin	—	68	—	Degree	G = 100V/V; 10 pF load
CM22	GM	Gain Margin	—	20	—	db	G = 100V/V; 10 pF load
CM23a	GBW	Gain Bandwidth	—	10	—	MHz	10 pF load
Op Amp DC Characteristics							
CM40	VCMR	Common-Mode Input Voltage Range	AVSS	—	AVDD	V	
CM41	CMRR	Common-Mode Rejection Ratio	—	40	—	db	VCM = AVDD/2
CM42	VOFFSET	Op Amp Offset Voltage	—	±20	±70	mV	
CM43	VGAIN	Open-Loop Voltage Gain	—	90	—	db	
CM44	IOS	Input Offset Current	—	—	—	—	See pad leakage currents in Table 33-10
CM45	IB	Input Bias Current	—	—	—	—	See pad leakage currents in Table 33-10
CM46	IOUT	Output Current	—	—	420	μA	With minimum value of RFEEDBACK (CM48)
CM48	RFEEDBACK	Feedback Resistance Value	8	—	—	kΩ	(Note 2)
CM49a	VOUT	Output Voltage	AVSS + 0.075	—	AVDD – 0.075	V	IOUT = 420 μA

Note 1: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

2: Resistances can vary by ±10% between op amps.

3: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter BO10 in Table 33-12 for the minimum and maximum BOR values.

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TABLE 33-57: ADCx MODULE SPECIFICATIONS (12-BIT MODE)

AC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
ADC Accuracy (12-Bit Mode) – VREF-							
AD20a	Nr	Resolution	12 data bits			bits	
AD21a	INL	Integral Nonlinearity	-3	—	+3	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V (Note 2)
AD22a	DNL	Differential Nonlinearity	≥ 1	—	< 1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V (Note 2)
AD23a	GERR	Gain Error	-10	—	10	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V (Note 2)
AD24a	EOFF	Offset Error	-5	—	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V (Note 2)
AD25a	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance (12-Bit Mode)							
AD30a	THD	Total Harmonic Distortion	—	—	-75	dB	
AD31a	SINAD	Signal to Noise and Distortion	68.5	69.5	—	dB	
AD32a	SFDR	Spurious Free Dynamic Range	80	—	—	dB	
AD33a	FNYQ	Input Signal Bandwidth	—	—	250	kHz	
AD34a	ENOB	Effective Number of Bits	11.09	11.3	—	bits	

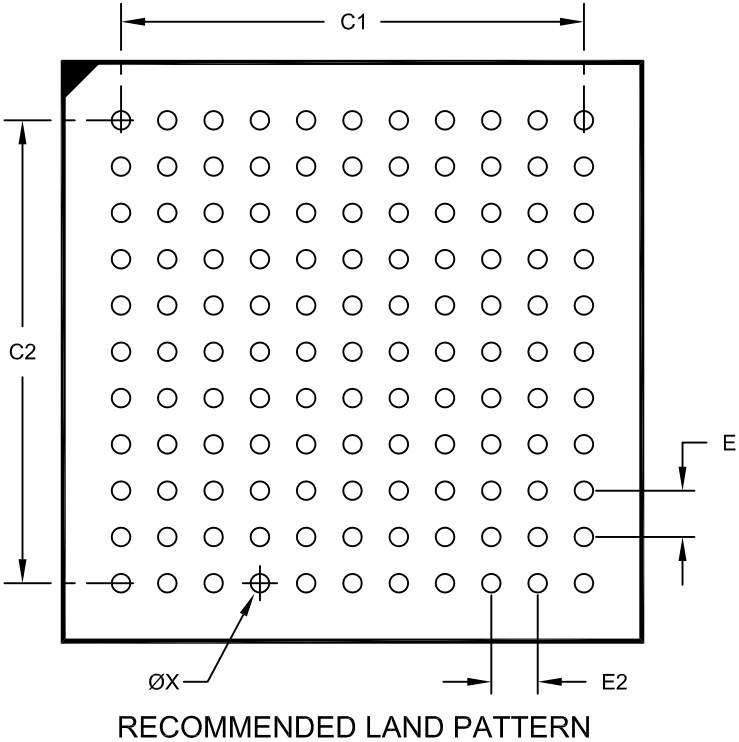
Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter BO10 in Table 33-12 for the minimum and maximum BOR values.

2: For all accuracy specifications, VINL = AVSS = VREFL = 0V and AVDD = VREFH = 3.6V.

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121-Lead Plastic Thin Profile Ball Grid Array (BG) - 10x10x1.10 mm Body [TFBGA--Formerly XBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E1	0.80 BSC		
Contact Pitch	E2	0.80 BSC		
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Diameter (X121)	X			0.32

Notes:

- 1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2148 Rev D